AD8137 Bill of Materials

Package	Body Size	Material	FROM Amkor Korea 1	TO STATS ChipPAC Malaysia
LFCSP	3x3	Die Attach	Ablestik 8290	Ablestik 8290
		Wire	1.0mil	1.0mil
		Mold Compound	Sumitomo G700	Sumitomo G700
		Leadframe	C194	C194